



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260715001.1	PCN Issued	July 15, 2026
Qualification of additional Assembly sites for select VSSOP device		Sample request deadline:	September 13, 2026
		Estimated 1st ship date:	October 13, 2026
Sample requests received after September 13, 2026 will not be supported.			

Change type(s)
Assembly Site
Assembly Material
Packing/Shipping/Labeling

PCN Details

Description of Change:	
Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information are as follows:	
VSSOP Build sites	
Assembly Sites	MLA, TIEM, HFTF, HNA
Mold Compound	4211880
	4222198
	SID#R-31
	SID#450179
	8096859
Mount Compound	4147858
	SID#A-18
	4213245
	SID#400180
	SID#400194
Wire	Au, Cu (0.8mil, 1.0mil)
Lead Frame Finish	NiPdAu, Matte Sn

Device marking:		
	Current	Additional
Marking differences	Pin 1 dimple Binary code □ □ □ □ * * * * {CUST1} ○ * * * * □ □ □ □	Pin 1 dot Mold cavity ID □ □ □ □ TI YM {CUST1} ○ (CAV) □ □ □ □

Qual details are provided in the Qual Data Section.	
Reason for Change:	Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or	Review the Standard Data Packet for more details on the changes
--	---

Reliability:																					
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table border="1"> <tr> <td>RoHS</td> <td>REACH</td> <td>Green Status</td> <td>IEC 62474</td> </tr> <tr> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> <td>☒ No Change</td> </tr> </table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change												
RoHS	REACH	Green Status	IEC 62474																		
☒ No Change	☒ No Change	☒ No Change	☒ No Change																		
Changes to product identification resulting from this PCN:	Assembly Site Information <table border="1"> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (23L)</th> <th>Assembly City</th> </tr> <tr> <td>MLA</td> <td>MLA</td> <td>MYS</td> <td>Kuala Lumpur</td> </tr> <tr> <td>HFTF</td> <td>HFT</td> <td>CHN</td> <td>Hefei</td> </tr> <tr> <td>TIEM</td> <td>CU6</td> <td>MYS</td> <td>Melaka</td> </tr> <tr> <td>HNA</td> <td>HNT</td> <td>THA</td> <td>Ayutthaya</td> </tr> </table> Sample product shipping label (not actual product label):	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	MLA	MLA	MYS	Kuala Lumpur	HFTF	HFT	CHN	Hefei	TIEM	CU6	MYS	Melaka	HNA	HNT	THA	Ayutthaya
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City																		
MLA	MLA	MYS	Kuala Lumpur																		
HFTF	HFT	CHN	Hefei																		
TIEM	CU6	MYS	Melaka																		
HNA	HNT	THA	Ayutthaya																		

Products Affected:			
74LVC1G123DCURE4	SN74LVC2G02DCUTG4	SN74LVC2G74DCUTE4	
74LVC1G123DCURG4	SN74LVC2G08DCUR4	SN74LVC2G74DCUTG4	
74LVC1G123DCUTG4	SN74LVC2G08DCURE4	SN74LVC3G07DCUR4	
74LVC2G157DCURG4	SN74LVC2G08DCURG4	SN74LVC3G07DCURG4	
74LVC2G157DCUTG4	SN74LVC2G08DCUT4	SN74LVC3G07DCUT4	
SN74LVC1G123DCUR4	SN74LVC2G08DCUTG4	SN74LVC3G07DCUTG4	
SN74LVC1G123DCUT4	SN74LVC2G157DCUR4	SN74LVC3G14DCUR4	
SN74LVC1G74DCUR4	SN74LVC2G157DCUT4	SN74LVC3G14DCURG4	
SN74LVC1G74DCURG4	SN74LVC2G32DCUR4	SN74LVC3G14DCUT4	
SN74LVC1G74DCUT4	SN74LVC2G32DCURE4	SN74LVC3G14DCUTG4	
SN74LVC2G00DCUR4	SN74LVC2G32DCURG4	SN74LVC3G17DCUR4	
SN74LVC2G00DCURE4	SN74LVC2G32DCUT4	SN74LVC3G17DCURG4	
SN74LVC2G00DCURG4	SN74LVC2G32DCUTG4	SN74LVC3G34DCUR4	
SN74LVC2G00DCUT4	SN74LVC2G74DCUR4	SN74LVC3G34DCURG4	

		4	
SN74LVC2G00DCUTG 4	SN74LVC2G74DCURE 4	SN74LVC3G34DCUT	
SN74LVC2G02DCUR	SN74LVC2G74DCURG 4	SN74LVC3G34DCUTG 4	
SN74LVC2G02DCUT	SN74LVC2G74DCUT		

Note: G4/E4 material will use NiPdAu lead finish



TI Information
Selective Disclosure

VSSOP Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	HFTF SN74LVC1G123DCU TMUX7219DGKQ1 SN74AXC2T45QDCURQ1	MLA SN74LVC2T45QDCURQ1 CLXC8T245QDGSQRQ1 LSF0108DGSR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	-	-
HTSL	High Temp. Storage Bake 150C	1000 hours	-	-
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAIST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	3/231/0
AC	Autoclave 121C	96 hours	-	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (PGA308AIDGSR)	3/66/0 (LMH5485DGKSEP)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	HNA TPS77301DGK TMP431ADGK SN74LVC2G125DCUR	TIEMA LM3489QMM LM5067MM-2NOPB
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	-
THB	Temperature Humidity Bias, 85C/85%RH	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 hours	1/77/0	-
AC	Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TS5A23160DGSR)	3/66/0 (LM2660MM/NOPB)
WBP	Wire Bond Pull	Wires	3/228/0	3/228/0
WBS	Wire Bond Shear	Wires	3/228/0	3/228/0
MQ	Manufacturability	-	Pass	Pass

CLXC8T245QDGSRQ1, TPS77301DGK, TMUX7219DGKQ1, LM3489QMM, LSF0108DGSR, LM5067MM-2NOPB, SN74LVC2T45QDCURQ1, SN74LVC1G123DCU, SN74AXC2T45QDCURQ1, SN74LVC2G125DCUR are qualified at L1-260C MSL rating.

TMP431ADGK is qualified at L2-260C MSL rating.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your

application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.